



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PCB Side View LED
- ▶ 1810SV (0704) 0.35t
- ▶ Sky White (Ice Blue)

NOW69S10SV-5MA



Release Date: 27 June 2026 Version: A1.0



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FEATURES:

- **Package:** PCB / CHIP LED Side View
- **Forward Current:** 5mA
- **Forward Voltage (typ.):** 2.9V
- **Luminous Intensity (typ.):** 230mcd@5mA
- **Colour:** Sky White (Ice Blue)
- **Colour Temperature (typ.):** X=0.2700; Y=0.2550
- **Viewing Angle (X/Y):** 140/120°
- **Materials:**
 - Resin: Epoxy (Yellow Diffused)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping Parameters:**
 - Forward voltage
 - Luminous intensity
 - CIE Chromaticity
- **Soldering Methods:** Reflow
- **MSL Level:** acc. to JEDEC Level 2a
- **Packing:** 8mm tape with max.4000/reel, ø178mm (7")

APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard
- Consumer Goods

CHARACTERISTICS:

Absolute Maximum Characteristics ($T_a=25^{\circ}\text{C}$)

Parameter	Symbol	Ratings	Unit
Forward Current	I_F	20	mA
Peak Forward Current Duty Cycle 1/10; 1KHz	I_{FP}	80	mA
Power Dissipation	P_D	78	mW
Reverse Voltage	V_R	5	V
Reverse Current @8V	I_R	10	μA
Operating Temperature	T_{OPR}	-40~+85	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-40~+100	$^{\circ}\text{C}$

Electrical & Optical Characteristics ($T_a=25^{\circ}\text{C}$)

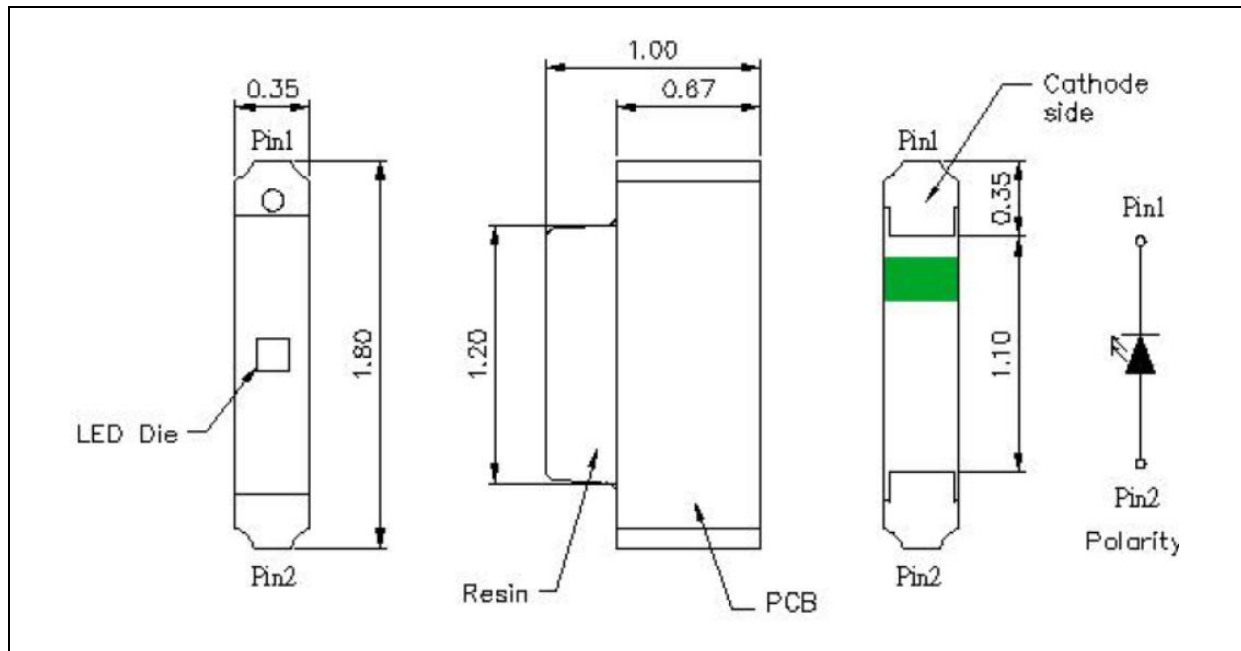
Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	---	2.9	3.25	V	$I_F=5\text{mA}$
Luminous Intensity	I_v	---	230	---	mcd	$I_F=5\text{mA}$
Chromaticity Coordinates	X	---	0.2700	---	---	$I_F=5\text{mA}$
	Y	---	0.2550	---		
Viewing Angle (X/Y)	$2\theta_{1/2}$	---	140/120	---	deg	$I_F=5\text{mA}$

1. Luminous intensity (I_v) $\pm 10\%$, Forward Voltage (V_F) $\pm 0.1\text{V}$.



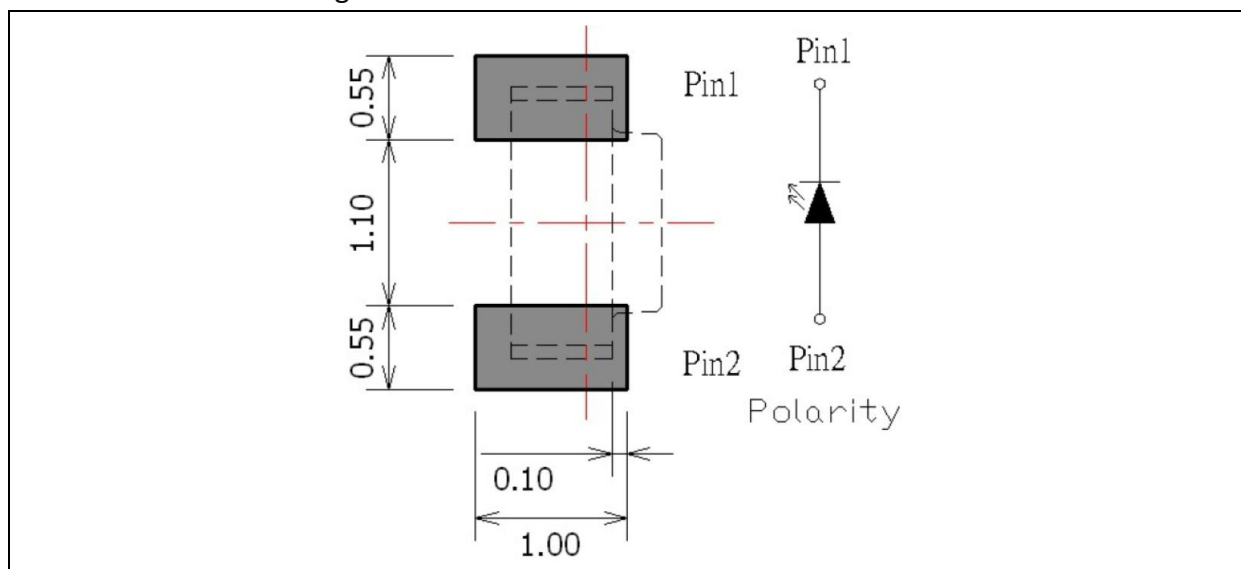
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

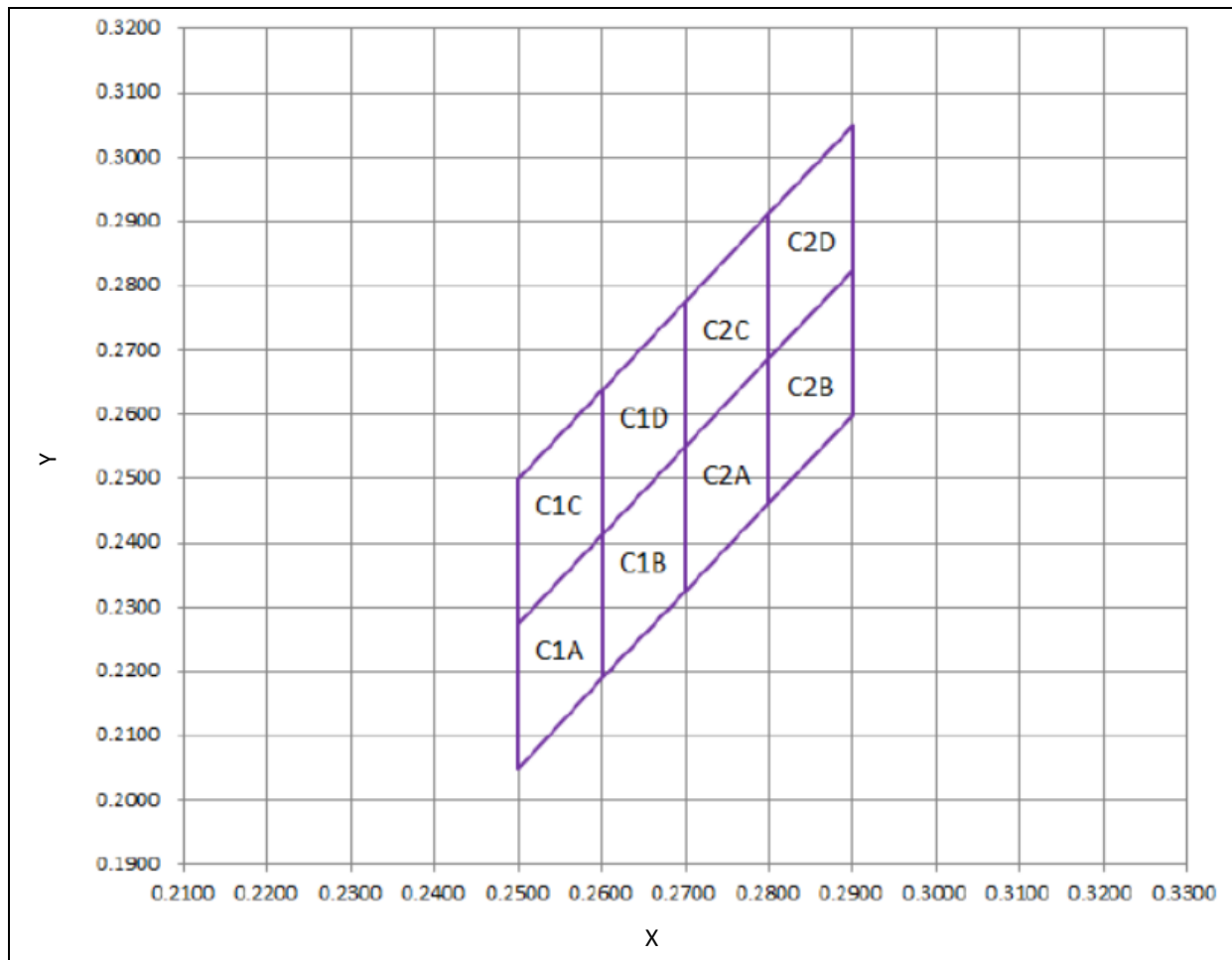
Forward Voltage Classifications ($I_F = 5\text{mA}$):

Code	Min.	Max.	Unit
G2T	2.55	2.65	V
G3T	2.65	2.75	
G4T	2.75	2.85	
H1T	2.85	2.95	
H2T	2.95	3.05	
H3T	3.05	3.15	
H4T	3.15	3.25	

Luminous Intensity Classifications ($I_F = 5\text{mA}$):

Code	Min.	Max.	Unit
Q2	90	112.5	mcd
R	112.5	180	
S	180	285	
T	285	360	

CIE CHROMATICITY DIAGRAM:

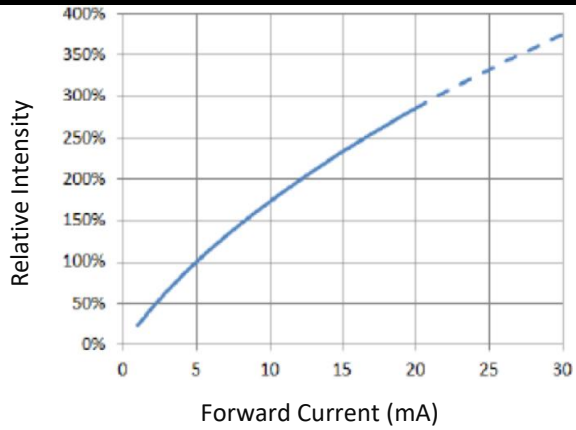


Chromaticity Coordinates Classifications ($I_F = 5\text{mA}$):

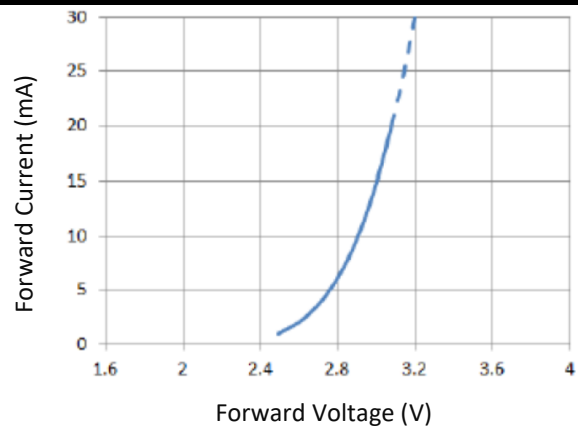
	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
C1A	0.2500	0.2050	0.2500	0.2275	0.2600	0.2415	0.2600	0.2190
C1B	0.2600	0.2190	0.2600	0.2415	0.2700	0.2550	0.2700	0.2325
C1C	0.2500	0.2275	0.2500	0.2500	0.2600	0.2640	0.2600	0.2415
C1D	0.2600	0.2415	0.2600	0.2640	0.2700	0.2775	0.2700	0.2550
C2A	0.2700	0.2324	0.2700	0.2550	0.2800	0.2688	0.2800	0.2463
C2B	0.2800	0.2463	0.2800	0.2688	0.2900	0.2825	0.2900	0.2600
C2C	0.2700	0.2550	0.2700	0.2775	0.2800	0.2913	0.2800	0.2688
C2D	0.2800	0.2688	0.2800	0.2913	0.2900	0.3050	0.2900	0.2825

ELECTRO-OPTICAL CHARACTERISTICS:

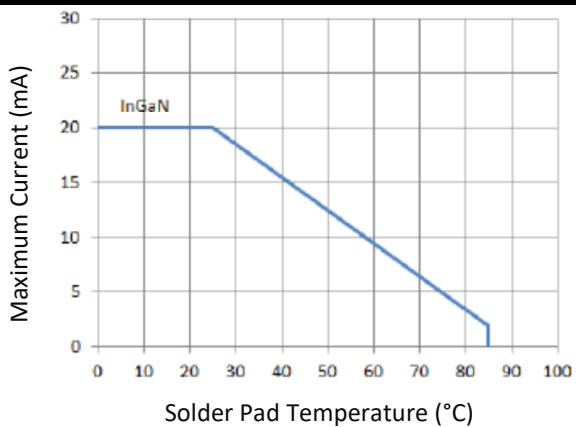
Relative Intensity vs. Forward Current



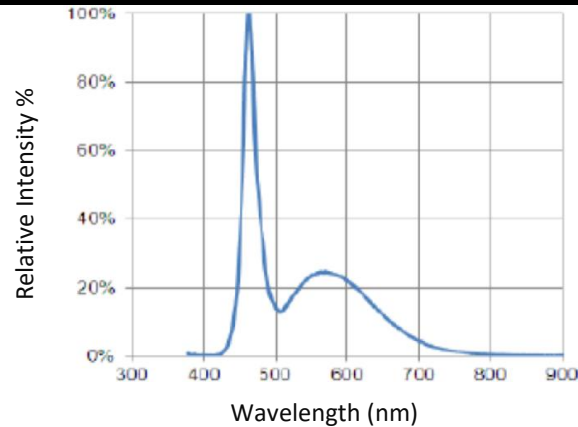
Forward Current vs. Forward Voltage



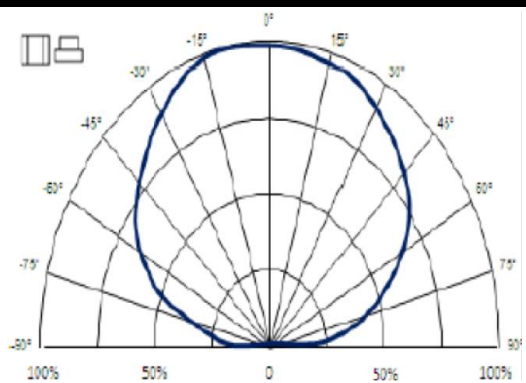
Temperature Derating Chart



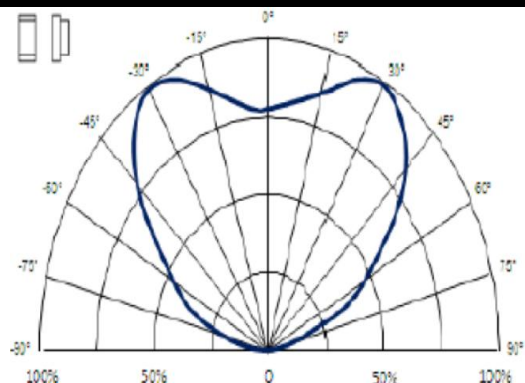
Relative Intensity vs. Wavelength



Directive Characteristics



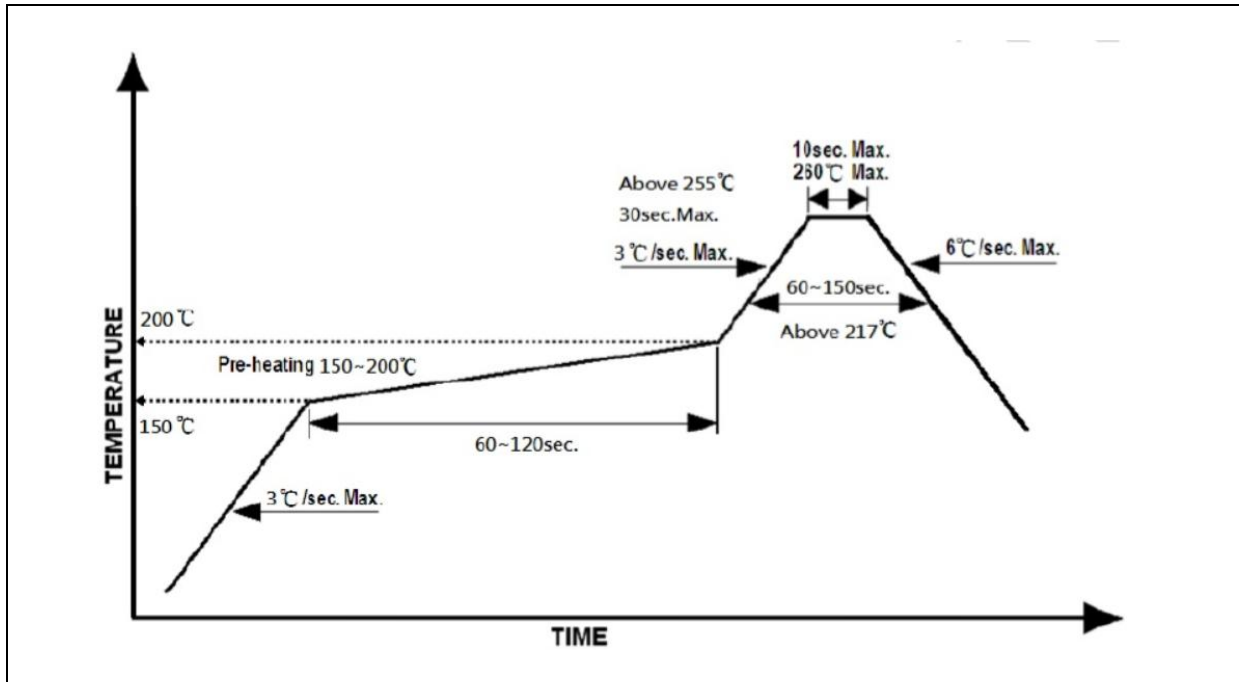
Directive Characteristics





RECOMMENDED SOLDERING PROFILE:

Reflow solder:



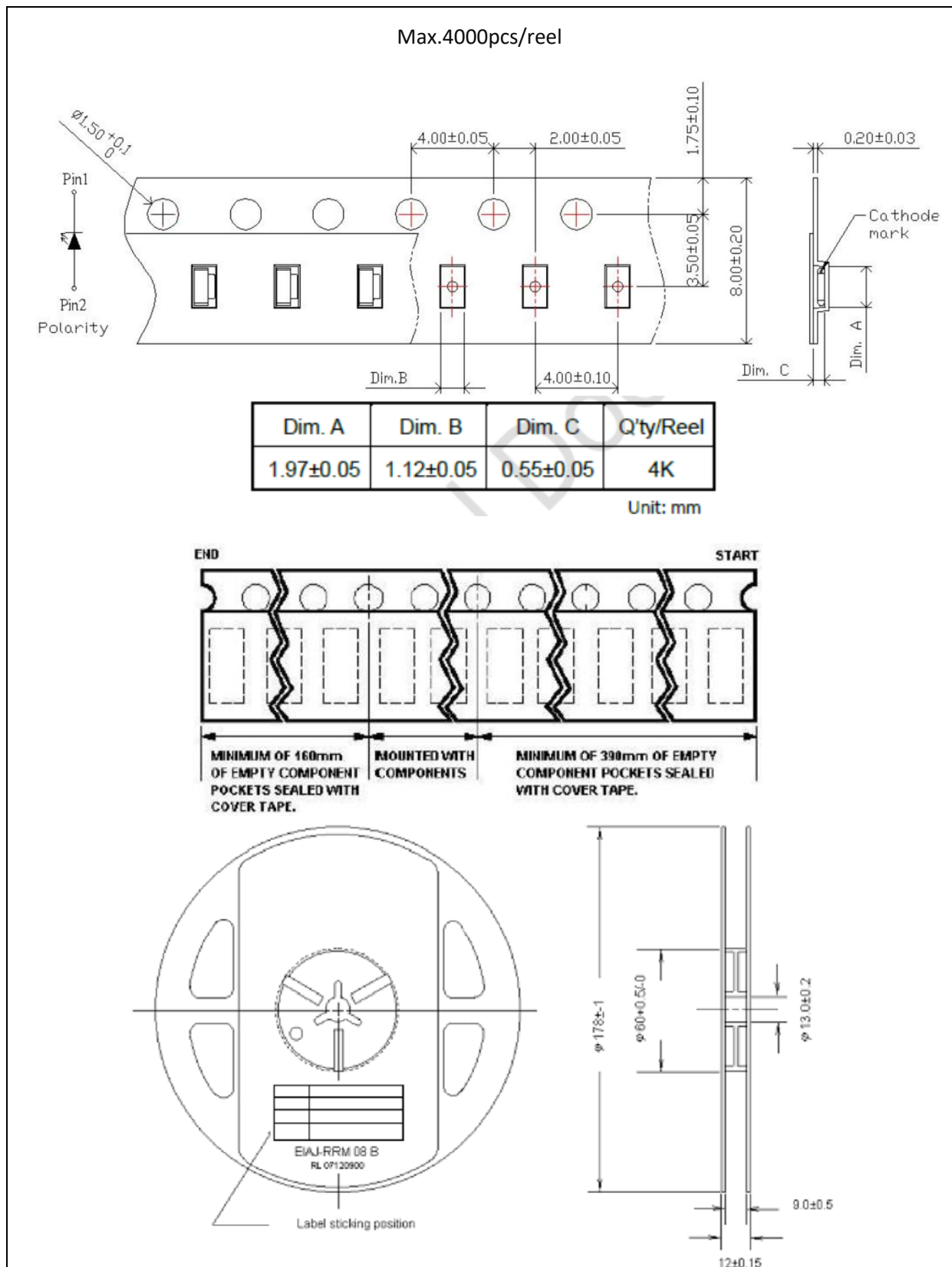
Note:

1. Recommend reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.
2. Maximum reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 4 weeks. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 4 weeks. The suggested baking conditions are as followings:

- 60±3°C x 12~24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	27/06/2026	Datasheet set-up.